

**What is claimed is:**

1. An anisotropic-electroconductive adhesive comprising:  
an insulating adhesive component containing a radical polymerizable compound  
5 and a polymerization initiator; and  
a plurality of insulating coated electroconductive particles dispersed in the insulating adhesive component, the insulating coated electroconductive particle having a coating layer made of insulating thermoplastic resin on a surface of an electroconductive particle,  
10 wherein a softening point of the insulating thermoplastic resin is lower than an exothermic peak temperature of the insulating adhesive component.
  
2. An anisotropic-electroconductive adhesive according to claim 1,  
wherein the exothermic peak temperature of the insulating adhesive component  
15 is in the range of 80°C ~ 120°C.
  
3. An anisotropic-electroconductive adhesive according to claim 1,  
wherein the coating layer made of the insulating thermoplastic resin has a thickness of 0.01 $\mu$ m ~ 10 $\mu$ m.  
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4. An anisotropic-electroconductive adhesive according to claim 1 or 3,  
wherein the electroconductive particle is made by forming a metal thin layer onto a surface of a nucleus material.
  
- 25 5. An anisotropic-electroconductive adhesive according to claim 1 or 2,

wherein the insulating adhesive component further includes thermosetting resin and a curing agent.

6. An anisotropic-electroconductive adhesive according to claim 1,  
5 wherein the radical polymerizable compound is acrylate based or metacrylate based compound.

7. An anisotropic-electroconductive adhesive according to claim 1 or 2,  
wherein the polymerization initiator is organic peroxide.

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8. An anisotropic-electroconductive adhesive according to claim 1 or 2,  
wherein the insulating adhesive component further includes thermoplastic resin.

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9. A circuit connection method comprising the steps of:  
(a) interposing an anisotropic-electroconductive adhesive including an insulating adhesive component containing a radical polymerizable compound and a polymerization initiator; and a plurality of insulating coated electroconductive particles dispersed in the insulating adhesive component, the insulating coated electroconductive particle having a coating layer made of insulating thermoplastic resin on a surface of an electroconductive  
20 particle, wherein a softening point of the insulating thermoplastic resin is lower than an exothermic peak temperature of the insulating adhesive component, between circuit boards respectively having circuit electrodes faced each other;

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(b) electrically connecting the faced circuit electrodes by removing a part of the insulating thermoplastic resin coating layer on the surface of the electroconductive particle contacted with the faced circuit electrodes by means of thermal pressing; and

(c) curing the insulating adhesive component so that the circuit electrodes are adhered and fixed.

10. A circuit connection structure in which the anisotropic-electroconductive  
5 adhesive defined in the claim 1 is interposed between circuit boards respectively having  
circuit electrodes faced each other so that the circuit electrodes are electrically  
connected each other.